

AMENDMENTS TO THE CLAIMS:

Please amend the claims as follows:

1-6. (Cancelled).

7. (Previously presented) A polishing method which is part of a method for fabricating a semiconductor device, the fabrication method including the process step of polishing a substrate using CMP,

wherein in the polishing process step, a tube-type slurry supply pump is used for supplying a slurry, and

wherein in the tube-type slurry supply pump, a tube which substantially does not contain fine particles for reinforcing the strength of the tube is used as a tube for supplying the slurry, and

wherein the tube is a vinyl chloride type tube.

8. (Cancelled)

9. (Previously presented) A method for fabricating a semiconductor device, comprising the polishing method of claim 7.

10. (Currently amended) A system for polishing a substrate using CMP, comprising:
a CMP apparatus for polishing the substrate; and
a tube-type slurry supply pump containing a tube for supplying a slurry during polishing,
~~wherein a tube for the tube-type slurry supply pump is a tube in which at least [[the]] an~~
~~inner surface of the tube~~ is formed of a vinyl chloride material, and
~~wherein the tube is a vinyl chloride type tube.~~

11-16. (Cancelled)

17. (Currently amended) A device formation method comprising the steps of:
placing a substrate in a CMP unit,
supplying a slurry on the substrate via a tube by a tube-type slurry supply pump through a
tube connected to a slurry pump, and
polishing the substrate on which the slurry is supplied,
wherein the tube has at least an inner surface of the tube is formed of a vinyl chloride
material.

18. (Currently amended) The device formation method of claim 17, A device formation
method comprising of,
placing a substrate in a CMP unit,
supplying a slurry on the substrate through a tube connected to a slurry pump, and
polishing the substrate on which the slurry is supplied,
wherein the tube is substantially formed of a vinyl chloride material type tube.

19. (Currently amended) The system for polishing a substrate using CMP of claim 10,
A system for forming a semiconductor device comprising:
a CMP unit for polishing a substrate;
a slurry pump for supplying a slurry to the CMP unit; and
a tube connected between the CMP unit and the slurry pump;
wherein the tube is substantially formed of a vinyl chloride material type tube.

20-21. (Cancelled)

22. (New) A polishing method of claim 7,
wherein the tube is repeatedly compressed by the tube-type slurry supply pump.
23. (New) A method for fabricating a semiconductor device of claim 9,
wherein the tube is repeatedly compressed by the tube-type slurry supply pump.
24. (New) A system for polishing a substrate using CMP of claim 10,
wherein the tube is repeatedly compressed by the tube-type slurry supply pump.
25. (New) A device formation method of claim 17,
wherein the tube is repeatedly compressed by the tube-type slurry supply pump.
26. (New) A polishing method of claim 7,
wherein a delivery roller repeatedly compresses the tube in the tube-type slurry supply pump.
27. (New) A method for fabricating a semiconductor device of claim 9,
wherein a delivery roller repeatedly compresses the tube in the tube-type slurry supply pump.
28. (New) A system for polishing a substrate using CMP of claim 10,
wherein a delivery roller repeatedly compresses the tube in the tube-type slurry supply pump.
29. (New) A device formation method of claim 17,
wherein a delivery roller repeatedly compresses the tube in the tube-type slurry supply pump.